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Ulrich Schmid
José Luis Sánchez de Rojas Aldavero
Monika Leester-Schaedel
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Introduction

The conference Smart Sensors, Actuators and MEMS took place in Grenoble, France from April 24th to April 26th, 2013. One hundred and fifteen contributions from Europe, America and Asia were accepted and grouped into 10 sessions including a poster session. The interdisciplinary spirit of the event was displayed by a wide range of topics based on the latest results which were achieved in the research and development areas of precision engineering and MEMS. Therefore, sessions focused on material and fabrication aspects, on micromachined sensors and actuators for the determination of biological, and physical and chemical quantities as well as on reliability issues. Moreover optical and RF MEMS have been presented and more application oriented topics such as energy scavengers, microfluidic systems, and low power management systems, were discussed. Due to this broad range of topics, researchers coming from academia and industry, with their specific backgrounds, created a very stimulating atmosphere for the exchange of new ideas.

Besides the high quality of the oral and poster presentations I would like to highlight the 4 invited presentations, given by Rob van Schaijk from IMEC, Belgium, on MEMS-based vibrational energy harvesters focusing automotive applications, by Vijaysekhar Jayaraman, Praevium Research Inc., United States, on MEMS-tunable VCSEL for imaging and spectroscopy, by Isabelle Dufour, University of Bordeaux, France, on the fluid-structure interaction of vibrating microcantilevers and last, but not least, by Stephanus Büttgenbach, Technische Universität Braunschweig, Germany, on electromagnetic microactuators.

I would like to thank all participants for their individual contributions which made the conference a successful event in the international conference calendar.

Special thanks go to Christos Tsamis, Gerhard Krötz and Thomas Becker for organising the symposium, and to my Co-Chairs José Luis Sánchez de Rojas Aldavero (Univ. Castilla-La Mancha, Ciudad Real, Spain) and Monika Leester-Schädel (Technische Universität Braunschweig, Germany). Finally I would like to thank the Programme Committee for doing the reviews and acting partly as session chairs.

Ulrich Schmid